

## LOCTITE ECCOBOND EN 3707F

November 2012

### PRODUCT DESCRIPTION

LOCTITE ECCOBOND EN 3707F provides the following product characteristics:

<b>Technology</b>	Epoxy
<b>Appearance</b>	Light yellow liquid
<b>Product Benefits</b>	<ul style="list-style-type: none"><li>• Dual cure</li><li>• Fast UV cure</li><li>• One component</li><li>• Cures in shadowed areas with heat</li><li>• Easy dispensability without stringing</li><li>• Fluorescent under UV light</li></ul>
<b>Cure</b>	Ultraviolet (UV) light or Heat cure
<b>Application</b>	Encapsulant
<b>Typical Assembly Applications</b>	Local protection of WLCSP and BGA on circuit board

LOCTITE ECCOBOND EN 3707F no flow encapsulant is designed for local circuit board protection. This adhesive cures in seconds when exposed to the appropriate intensity of UV light. In addition to light cure, this adhesive contains a secondary thermal cure initiator.

### TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 20 rpm	3,480
Pot Life @ 25°C, days	3
Flash Point - See MSDS	

### TYPICAL CURING PERFORMANCE

#### Recommended UV Cure Condition

Light Source and Condition:	
UVA or UVB light	
Light Intensity, mW/cm <sup>2</sup>	100
Exposure Time, seconds	>30

#### Depth of Cure

Medium Pressure Hydrargyrum Light:	
100 mW/cm <sup>2</sup> , for 30 seconds, mm:	≥10

#### Recommended Heat Cure

30 minutes @ 80°C
5 minutes @ 100°C
1 to 2 minutes @ 130°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

### TYPICAL PROPERTIES OF CURED MATERIAL

#### Physical Properties:

Coefficient of Thermal Expansion, TMA:	
Below Tg, ppm/°C	50.3
Above Tg, ppm/°C	162.2
Glass Transition Temperature (Tg) by TMA, °C	36.8
Storage Modulus, DMA:	
@ 25°C	N/mm <sup>2</sup> 4,400 (psi) (638,000)

### GENERAL INFORMATION

**For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).**

#### THAWING:

1. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the warmed up container should be removed prior to opening the container.
2. Syringes should be positioned tip down when stored vertically.
3. Once material has reached room temperature, the adhesive should not be re-refrigerated.

#### DIRECTIONS FOR USE

1. This product is light sensitive; exposure to daylight, UV light or artificial lighting should be kept to a minimum during storage and handling.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 2 to 8°C. Storage below 2°C or above 8°C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

## Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$   
 $\text{kV/mm} \times 25.4 = \text{V/mil}$   
 $\text{mm} / 25.4 = \text{inches}$   
 $\text{N} \times 0.225 = \text{lb}$   
 $\text{N/mm} \times 5.71 = \text{lb/in}$   
 $\text{N/mm}^2 \times 145 = \text{psi}$   
 $\text{MPa} \times 145 = \text{psi}$   
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$   
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$   
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$   
 $\text{mPa}\cdot\text{s} = \text{cP}$

## Disclaimer

### Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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